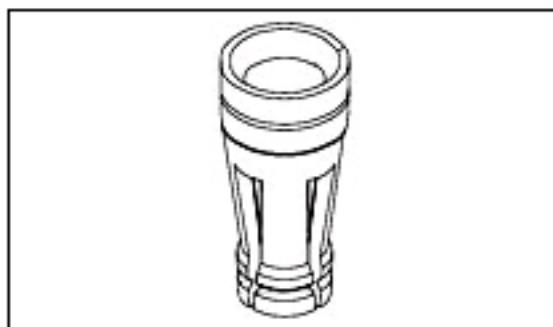




What can we help you find?

M8134-HC-5P2 Product Details

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M8134-HC-5P2
(8-1437514-0)

TE Internal Number: 8-1437514-0

Active

View 3D PDF

Discrete Sockets

Always EU RoHS/ELV Compliant (Statement of Compliance)

Product Highlights:

- HOLTITE Product Line
- Board-to-Device
- Applies To Printed Circuit Board
- Contact - Rated Current = 5 A
- Mating Pin Dia. Range = .41 - .534 mm

[View all Features](#)

Quick Links

- ▶ Pricing & Availability
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Documentation & Additional Information

Product Drawings:

- [HOLTITE CONTACTS](#) (PDF, English)

Catalog Pages/Data Sheets:

- None Available

Product Specifications:

- [AUGAT HOLTITE Sockets](#) (PDF, English)

Application Specifications:

- [AUGAT HOLTITE Sockets](#) (PDF, English)

Instruction Sheets:

- None Available

CAD Files: (CAD Format & Compression Information)

- [2D Drawing](#) (DXF, Version C)
- [3D Model](#) (IGES, Version C)
- [3D Model](#) (STEP, Version C)

[List all Documents](#)

Additional Information:

- [Product Line Information](#)

Related Products:

- [Tooling](#)

Product Features (Please use the Product Drawing for all design activity)

Product Type Features:

- Product Line = HOLTITE
- Socket Length (mm [in]) = 2.39 [0.094]
- Sealant = Without
- Profile = Zero

Electrical Characteristics:

- Contact - Rated Current (A) = 5

Termination Features:

- Insertion Method = Hand/Semi-Automatic

Dimensions:

- Recommended Hole Size (mm [in]) = 1.04 [0.041]

Body Features:

- Mating Pin Dia. Range (mm [in]) = 0.41 - 0.534 [0.017 - 0.021]

Contact Features:

- Contact Plating, Mating Area, Material = Gold
- Contact Plating, Mating Area, Thickness (µm [µin]) = 0.00076 [0.03]
- Contact Type = Socket
- Contact Base Material = Beryllium Copper

Industry Standards:

- Government/Industry Qualification = Yes
- Government/Industry Part Number = M83505/6-001
- RoHS/ELV Compliance = RoHS compliant, ELV compliant
- Lead Free Solder Processes = Not relevant for lead free process
- RoHS/ELV Compliance History = Always was RoHS compliant

Conditions for Usage:

- Applies To = Printed Circuit Board

Operation/Application:

- Application Use = Board-to-Device
- Contact Transmits (Typical Application) = Signal (Data)/Power

Packaging Features:

- Packaging Method = Loose Piece

Other:

- Brand = AMP

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